

View Online at <https://aerobasegroup.com/nsn/5910-01-388-5892>

**Body Style:**

Chip type

**Reliability Indicator:**

Established

**Reliability Failure Rate Level In Percent:**

0.100

**Body Length:**

Between 0.090 inches and 0.145 inches

**Body Width:**

0.110 inches

**Body Height:**

Between 0.030 inches and 0.102 inches

**Schematic Diagram Designator:**

No common or grounded electrode (s)

**Insulation Resistance At Maximum Operating Temp:**

100000.0 megohms

**Capacitance Value Per Section:**

4.700 picofarads single section

**Nonderated Operating Temp:**

Between -55.0 degrees celsius and 125.0 degrees celsius

**Temperature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius:**

90.0 single section

**Nonderated Continuous Voltage Rating And Type Per Section:**

500.0 dc single section

**Tolerance Of Temperature Coefficient Per Section In Ppm Per Deg Celsius:**

-20.0/+20.0 single section

**Tolerance Range Per Section:**

-0.25/+0.25 picofarads single section

**Case Material:**

Ceramic

**Insulation Resistance At Reference Temp:**

100000.0 megohms

**Dissipation Factor At Reference Temperature In Percent:**

0.050

**Reference Temperature At Which Rated:**

25.0 degrees celsius

**Terminal Surface Treatment:**

Solder

**Test Data Document:**

81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

**Terminal Type And Quantity:**

2 bonding pad

**Specification Data:**

81349-mil-c-55681/4 government specification

**Shelf Life:**

N/a

**Unit Of Measure:**

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**Demilitarization:**

No

**Fiig:**

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